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| U.S. Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) | Attorney Docket No.: UMC-96-279 | Serial No.: Not Assigned 08/958, 460 |
| | Applicants: Chih-Chien Liu, et al. | |
| | Filing Date: Herewith 10/28/97 | Art Group: Not Assigned 1700 |

U.S. PATENT DOCUMENTS

| Examiner Initial | Document Number | Date | Name | Class | Sub- Class | Filing Date if Appro- priate |
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FOREIGN PATENT DOCUMENTS

| Document Number | Date | Country | Class | Sub- Class | Trans- lation Yes/No |
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

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| RA | J.T. Pye, et al., "High-Density Plasma CVD and CMP for 0.25- μ m Intermetal Dielectric Processing," Solid State Technology, December 1995, pp.65-69. |
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EXAMINER

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